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(54) Title: DEFORMABLE SUBSTRATE ASSEMBLY FOR ADHESIVELY BONDED ELECTRONIC DEVICE

(57) Abstract

The present invention relates to a deformable substrate assembly (20) for microelectronic components (10) which includes an array of ductile metal circuit traces (22) on a surface thereof. When an electronic component is adhesively bonded to the substrate assembly, and bonding elements (16) from the component contact the traces, the substrate has material properties which allow individual bonding elements to locally deform the traces until the traces penetrate into the substrate surface.

